

L Number	Hits	Search Text	DB	Time stamp
1	0	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and "180.degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 13:00
2	0	"180.degree. C." same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:58
3	0	"180.degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:59
4	0	"180.degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:59
5	0	".degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:59
6	10018	degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:48
7	74	(degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:47
8	51	((degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((metal\$4 nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:55
10	8887	(degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:49
9	35	(degree?C and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near5 (hot heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:51

12	24	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near5 (hot heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 15:04
14	2576	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((metal\$4 nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:57
15	2576	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((metal\$4 nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet board)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 14:57
16	6	((degree?f or degree?C) and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) and ((polymer\$4 elastomer\$4 plastic\$4) near5 (hot heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4) near6 ((metal\$4 nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet board))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 15:07
17	4	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same (polymer\$4 near5 (hot heat\$4 warm\$4 temperature) near4 (bind\$4 cur\$4) near6 ((metal\$4 nickel alum\$4 iron silver gold copper) near4 (film layer plate sheet board))))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 15:07
-	213	73/827.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:16
-	123	73/834.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:16
-	47	73/835.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:16
-	2993	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 plate)) same (polymer\$4 plastic\$4) same (hot heat\$4 warm\$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:40
-	35	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 plate)) same (polymer\$4 plastic\$4) same (hot heat\$4 warm\$4 temperature)) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:45
-	310	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 plate)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:46

-	9	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 near4 plate)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 10:36
-	7	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 plate)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature)) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:55
-	75	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 near4 plate)) and (((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:59
-	0	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4 near4 plate)) and (((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 deposit\$4 set\$4)) same (hot heat\$4 warm\$4 temperature))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:58
-	2548	73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 15:59
-	2	(73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and ((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate layer specimen cable wire) near4 ((metal\$4 conductive) near4 (sheet layer board plate) near6 (hot heat\$4 warm\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:11
-	2	(73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and ((secur\$4 bind\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate layer specimen cable wire) near4 ((metal\$4 conductive) near4 (sheet layer board plate) near6 (hot heat\$4 warm\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:14
-	38	(73/\$6.ccls. and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and ((secur\$4 bind\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate layer specimen cable wire sheet layer board plate) near6 (hot heat\$4 warm\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/08 17:15
-	2	("5641913" "5969262").PN.	USPAT	2003/08/08 17:16
-	137	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 plate) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 11:09
-	1	((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 plate) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 12:39

-	37	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 13:21
-	2	6455152.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 12:46
-	65	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 16:13
-	81	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:08
-	11	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire) near4 (metal\$4)) same ((polymer\$4 elastomer\$4 glu\$4 adhe\$5 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/11 17:13
-	26	((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:47
-	0	(((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and "180.degree. C."	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 11:48
-	0	(((((secur\$4 fix\$4 adher\$4 bond\$4 join\$4 glu\$4 stick\$4 attach\$4) near6 (film substrate specimen cable wire)) same ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)) same ((hot heat\$4 warm\$4 temperature) near4 (platform plate\$2 surface base support\$4))) and ((pull\$4 tear\$4 tension\$4 separat\$4 remov\$4 strength detach\$4 stretch\$4 draw\$4) near6 (measur\$4 meter\$4 estimat\$4 detect\$4 determin\$4 test\$4 sens\$4 monitor\$4 bond\$4) near4 (forc\$4 load\$4 strain\$4 stress\$4))) and "177.degree. C." and ((polymer\$4 elastomer\$4 plastic\$4) near4 (appli\$5 apply\$4 put\$4 bind\$4 deposit\$4 set\$4 cur\$4)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/08/12 12:55